

L Number	Hits	Search Text	DB	Time stamp
1	2	substrate and (chip die IC) and ((flash-proof) (flash adj proof))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 10:27
2	1621	257/79-114.ccls. and substrate and (ic die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:23
3	2	("20020089832").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:21
4	0	huan-chien-ping.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:21
5	0	huan-chienping.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:21
6	2	huan-ping.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:21
7	875	257/81-82,91,88,99,100,103.ccls. and substrate and (ic die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:25
8	415	257/81-82,91,88,99,100,103.ccls. and substrate and (ic die chip) and (encapsulat\$4 mold\$4 hous\$4 packag\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:47
9	1439	257/704-720,678-681,687-689.ccls. and substrate and (ic die chip) and (encapsulat\$4 mold\$4 hous\$4 packag\$4) and (heat adj (sink element plug spread\$4 plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:55
10	2	("6191360").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/17 12:55